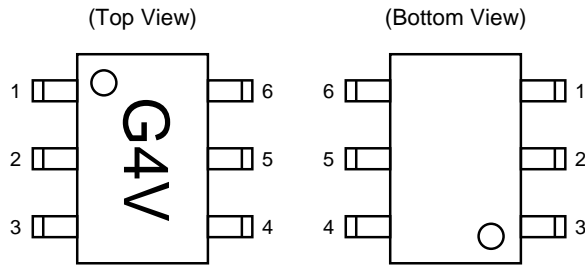


PIN CONNECTIONS



Pin No.	Pin Name
1	OUT2
2	GND
3	OUT1
4	V _{DD}
5	IN
6	V _{cont}

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{DD}	+8.0	V
Control Voltage	V _{cont}	+8.0	V
Input Power	P _{in}	+38	dBm
Operating Ambient Temperature	T _A	-45 to +85	°C
Storage Temperature	T _{stg}	-55 to +150	°C

RECOMMENDED OPERATING RANGE (T_A = +25°C)

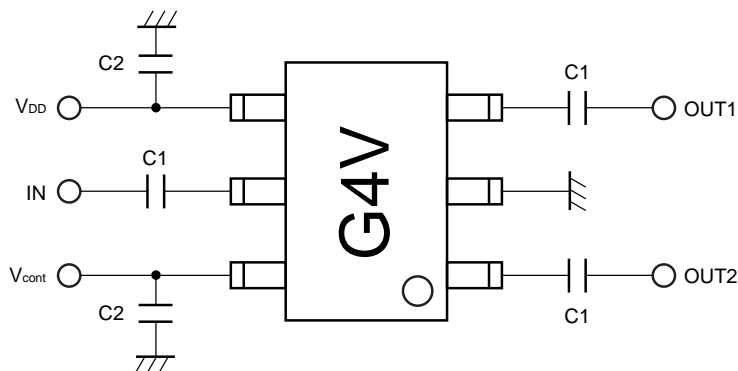
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{DD}	+2.4	+2.6	+5.0	V
Control Voltage (High)	V _{cont (H)}	+2.4	+2.6	+5.0	V
Control Voltage (Low)	V _{cont (L)}	0	0	+0.2	V

ELECTRICAL CHARACTERISTICS ($T_A = +25^\circ\text{C}$, $V_{DD} = +2.6\text{ V}$, $V_{cont} = +2.6\text{ V/0 V}$, $Z_o = 50\ \Omega$, off chip DC blocking capacitors value: 56 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	Pass	MIN.	TYP.	MAX.	Unit
Insertion Loss	L_{INS}	f = 0.8 to 1.0 GHz	IN-OUT1	–	0.45	0.65	dB
			IN-OUT2	–	0.35	0.55	dB
		f = 1.0 to 2.0 GHz	IN-OUT1/2	–	0.45	0.65	dB
		f = 2.0 to 2.5 GHz	IN-OUT1/2	–	0.50	–	dB
Isolation	ISL	f = 0.8 to 1.0 GHz	IN-OUT1/2	21.0	23.0	–	dB
		f = 1.0 to 2.0 GHz	IN-OUT1/2	15.5	17.5	–	dB
		f = 2.0 to 2.5 GHz	IN-OUT1/2	–	16.0	–	dB
Input Return Loss	RL_{in}	f = 0.8 to 1.0 GHz	IN-OUT1	10	15	–	dB
			IN-OUT2	15	20	–	dB
		f = 1.0 to 2.0 GHz	IN-OUT1/2	15	20	–	dB
		f = 2.0 to 2.5 GHz	IN-OUT1/2	–	20	–	dB
Output Return Loss	RL_{out}	f = 0.8 to 1.0 GHz	IN-OUT1	10	15	–	dB
			IN-OUT2	15	20	–	dB
		f = 1.0 to 2.0 GHz	IN-OUT1/2	15	20	–	dB
		f = 2.0 to 2.5 GHz	IN-OUT1/2	–	20	–	dB
0.1 dB Loss Compression Input Power	$P_{in(0.1\text{ dB})}$	f = 1.0 GHz	IN-OUT1/2	35	37	–	dBm
		f = 2.0 GHz	IN-OUT1/2	35	37	–	dBm
2nd Harmonics	2f ₀	f = 1.0 GHz, $P_{in} = +35\text{ dBm}$	IN-OUT1/2	65	75	–	dBc
		f = 2.0 GHz, $P_{in} = +33\text{ dBm}$	IN-OUT1/2	65	70	–	dBc
3rd Harmonics	3f ₀	f = 1.0 GHz, $P_{in} = +35\text{ dBm}$	IN-OUT1/2	65	75	–	dBc
		f = 2.0 GHz, $P_{in} = +33\text{ dBm}$	IN-OUT1/2	65	75	–	dBc
Switching Speed	t_{sw}			–	1	5	μs
Control Current	I_{cont}	No RF		–	5	50	μA
Supply Current	I_{DD}	No RF		–	40	200	μA

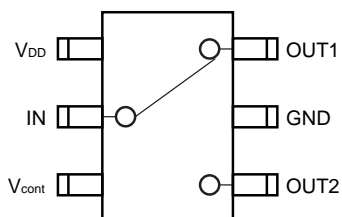
EVALUATION CIRCUIT

Off chip DC blocking capacitors value C1 = 56 pF, C2 = 1 000 pF (Bypass), using NEC standard evaluation board.



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

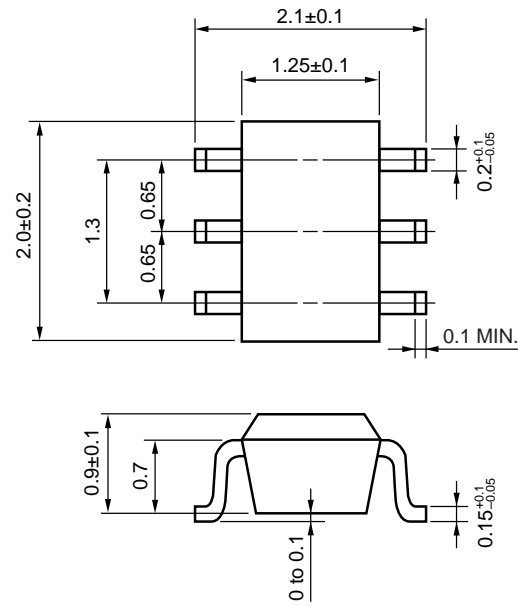
TRUTH TABLE



V _{cont}	IN-OUT1	IN-OUT2
High	OFF	ON
Low	ON	OFF

PACKAGE DIMENSIONS

6-PIN SUPER MINIMOLD (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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